









# PRODUCT DATASHEET



- ➤ Subminiature SMD (Reverse Mount)
- 2520RV Series
- ► Green (574nm)

N0G09S54RV



# **2520RV Series**





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#### **APPLICATIONS:**

- Backlighting
- Indication Light
- Switch light
- Dashboard

## **FEATURES:**

- Package: Reverse Mount Subminiature SMD
- Forward Current: 20mA
- Forward Voltage (typ.): 2.2V
- Luminous Intensity (typ.): 550mcd @20mA
- Colour: Green
- Wavelength: 574nm
- Viewing angle: 20°
- **Materials:** 
  - Die: AlGaInP
  - Resin: Epoxy (Water Clear)
- Operating Temperature: -40~+85°C
- Storage Temperature: -40~+100°C
- **ESD:** 2000V
- **Grouping parameters:** 
  - Forward voltage
  - Luminous intensity
  - **Dominant Wavelength**
- Soldering methods: Reflow
- Preconditioning: acc. to JEDEC Level 3
- Packing: 12mm tape with 1500/reel, ø180mm (7")



# **CHARACTERISTICS:**

# Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I <sub>F</sub>	30	mA
Peak Forward Current Duty 1/10@10KHz	I <sub>FP</sub>	60	mA
Reverse Current @5V	I <sub>R</sub>	10	μΑ
Power Dissipation	PD	75	mW
Electrostatic Discharge	ESD	2000	V
Operating Temperature	$T_OPR$	-40~+85	°C
Storage Temperature	T <sub>STG</sub>	-40~+100	°C

# Electrical & Optical Characteristics (Ta=25°C)

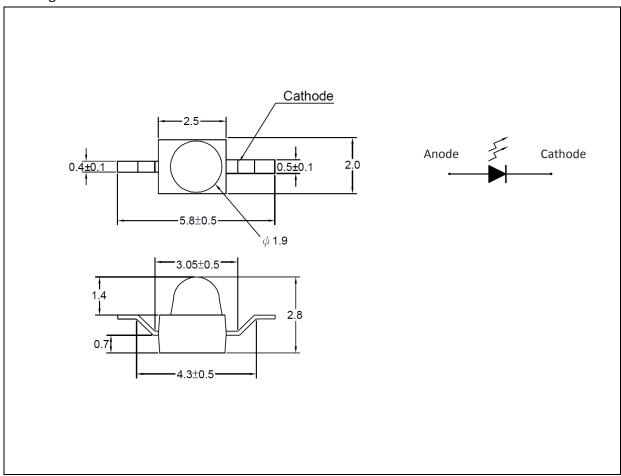
Parameter	Symbol		Values			Test
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	$V_{F}$	1.6		2.6	V	I <sub>F</sub> =20mA
Luminous Intensity	I <sub>V</sub>	350	550		mcd	I <sub>F</sub> =20mA
Dominant Wavelength	$\lambda_{\scriptscriptstyle D}$		574		nm	I <sub>F</sub> =20mA
Spectral Line Half Bandwidth	Δλ		20		nm	I <sub>F</sub> =20mA
Viewing Angle	2θ <sub>1/2</sub>		20		deg	I <sub>F</sub> =20mA

<sup>1.</sup> Luminous intensity (I $_{V}$ ) ±15%, Forward Voltage (V $_{F}$ ) ±0.1V



# **OUTLINE DIMENSION:**

# Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.



# **BINNING GROUPS:**

# Forward Voltage Classifications (I<sub>F</sub> = 20mA):

Code	Min.	Max.	Unit
1	1.6	1.8	
2	1.8	2.0	
3	2.0	2.2	V
4	2.2	2.4	
5	2.4	2.6	

# Luminous Intensity Classifications (I<sub>F</sub> = 20mA):

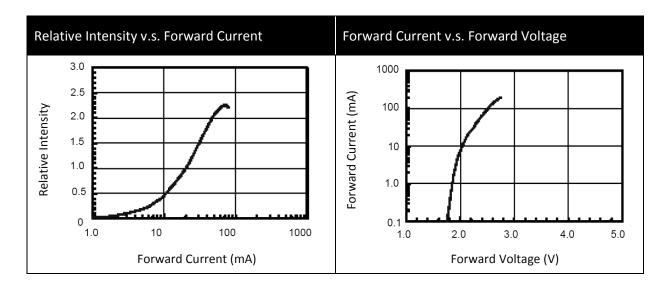
Code	Min.	Max.	Unit
G1	350	450	
G2	450	550	mad
G3	550	650	mcd
G4	650	750	

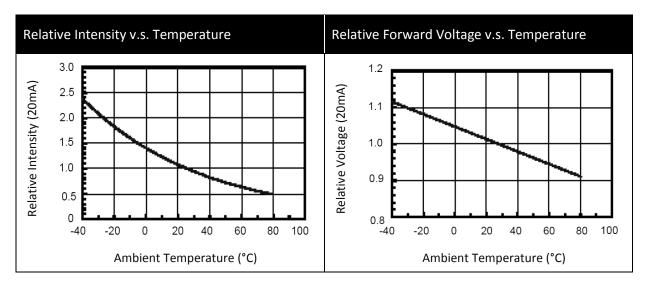
# Dominant Wavelength Classifications ( $I_F = 20$ mA):

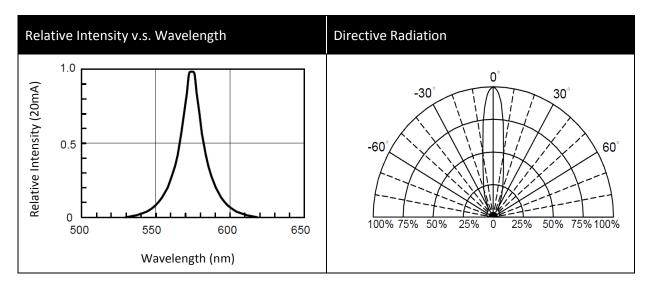
Code	Min.	Max.	Unit
H1	570	574	
H2	574	578	nm



#### **ELECTRO-OPTICAL CHARACTERISTICS:**



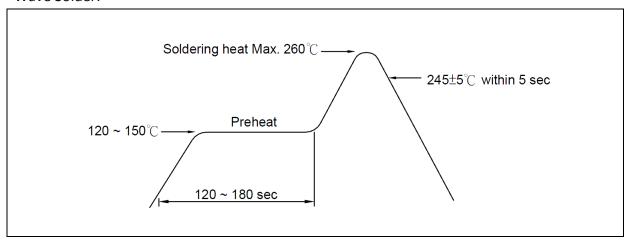




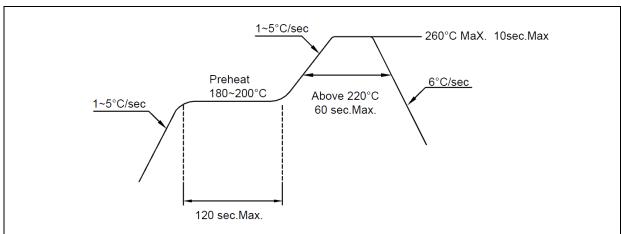


### **RECOMMENDED SOLDERING PROFILE:**

#### Wave Solder:



#### Lead-free Solder:



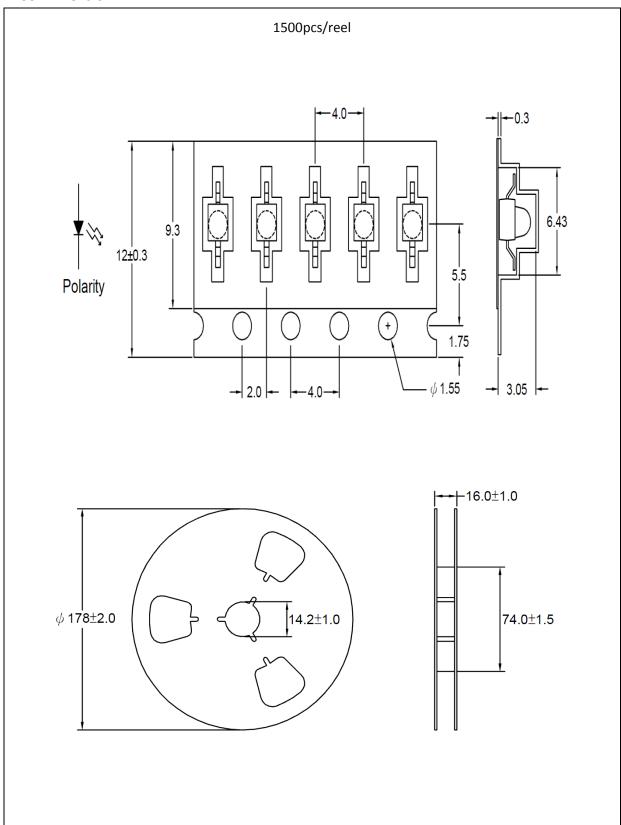
#### Note:

- 1. Maximum reflow soldering: 2 times.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



# **PACKING SPECIFICATION:**

#### Reel Dimension:





#### **PRECAUTIONS OF USE:**

#### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

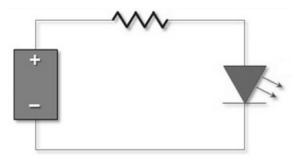
#### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

### **Testing Circuit:**



Must apply resistor(s) for protection (over current proof).

### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

#### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



# **REVISION RECORD:**

Version	Date	Summary of Revision
A1.0	20/02/2014	Datasheet set-up.
A1.1	16/07/2014	Revise picture and series.
A1.2	17/10/2014	Minor wording change.
A1.3	17/11/2015	Part number adds suffix -RV to indicate reverse mount.